

Features

- ESD Protection >30kV (Human Body Model) (Note 1)
- Ultra-Small Surface Mount Package
- Protects 2 Data Lines
- Low Leakage <25nA
- Low Capacitance 3pF Typ.
- Protects USB 2.0 and USB 1.1
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 2, 3 and 4)**

EC Compatibility (Note 1)

- 61000-4-2 (ESD) Air-30kV Contact-30kV
- 61000-4-4 (EFT) 40A, 5/50 ns
- 61000-4-5 (Surge) 8x20μs, 20 Amperes

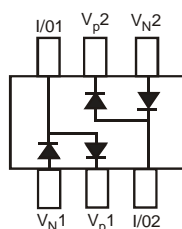
Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Orientation: See Diagram Below
- Weight: 0.006 grams (approximate)

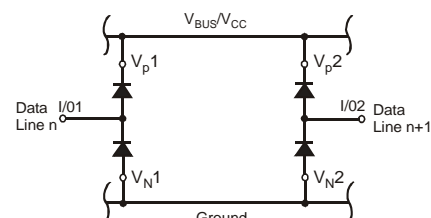
SOT-363



Top View



Internal Schematic



APPLICATION

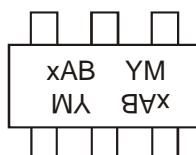
Top View

Ordering Information (Note 5)

Part Number	Case	Packaging
SDA004-7	SOT-363	3000/Tape & Reel

- Notes:
1. Tested with V_P connected to V_N to simulate appropriate V_{BUS}/V_{CC} decoupling to ground.
 2. No purposefully added lead. Halogen and Antimony Free.
 3. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
 4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.
 5. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



KAB or JAB = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: R = 2004
 M = Month ex: 9 = September

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	R	S	T	U	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	80	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Forward Continuous Current (Note 6)	I _{FM}	500	mA
Repetitive Peak Forward Current @ T _p = 5μs, f = 50kHz (Note 6)	I _{FRM}	1000	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	20	A
		1.0	
Clamping Voltage @ I _{pp} = 20A (Note 7) 8x20μs Waveform	V _C	16	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	200	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V _{(BR)R}	80	—	—	V	I _R = 100μA
Forward Voltage	V _F	0.62	—	0.72	V	I _F = 5.0mA
		—		0.93		I _F = 20mA
		—		1.0		I _F = 100mA
		—		1.25		I _F = 150mA
Reverse Current (Note 8)	I _R	—	—	100	nA	V _R = 70V
				50	μA	V _R = 75V, T _J = 150°C
				30	μA	V _R = 25V, T _J = 150°C
				25	nA	V _R = 20V
Capacitance, Between I/O Lines (I/O1 & I/O2)	C _{LL}	—	2.5	4.0	pF	V _R = 0V, f = 1.0MHz
Capacitance Between I/O Line and Ground	C _{LG}	—	3.3	5.3	pF	V _R = 0V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	4.0	ns	V _R = 6V, I _F = 5mA

- Notes:
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
 - Referenced to V_P or V_N.
 - Short duration pulse test used to minimize self-heating effect.

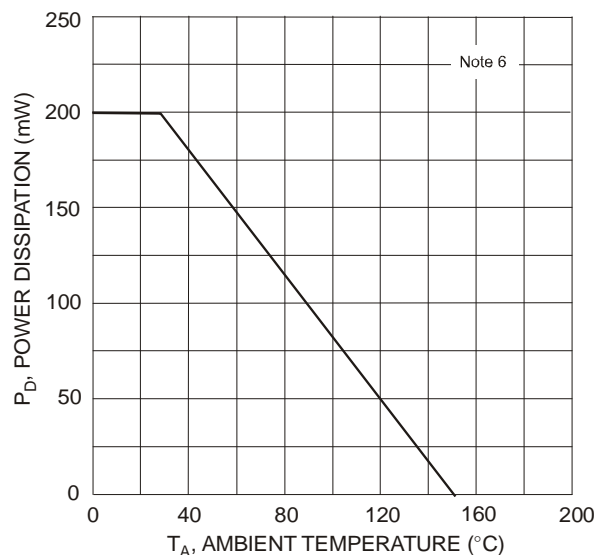


Fig. 1 Power Derating Curve, Total Package

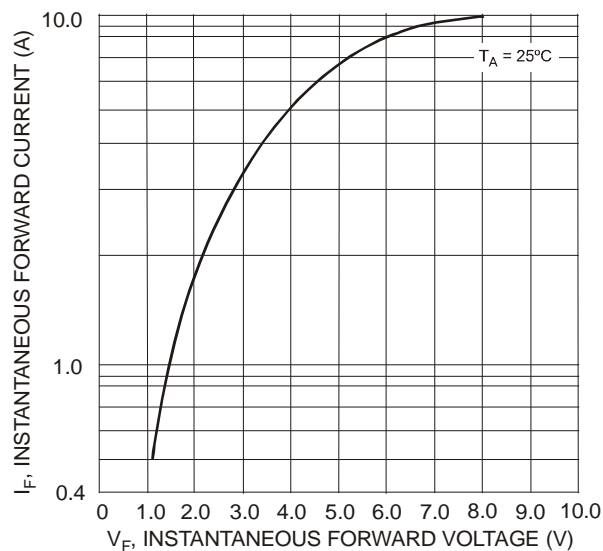


Fig. 2 Typical Forward Characteristics, High Current, Per Element

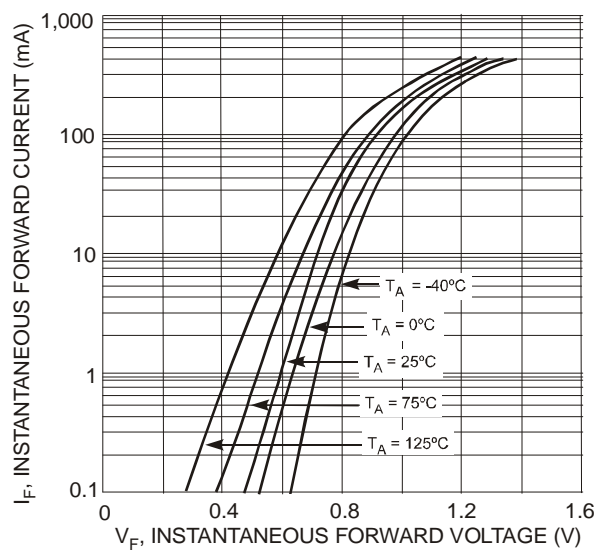


Fig. 3 Typical Forward Characteristics, Low Current, Per Element

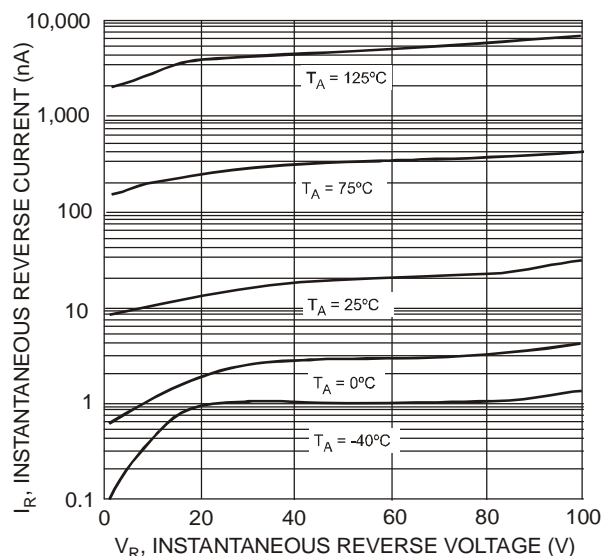


Fig. 4 Typical Reverse Characteristics, Per Element

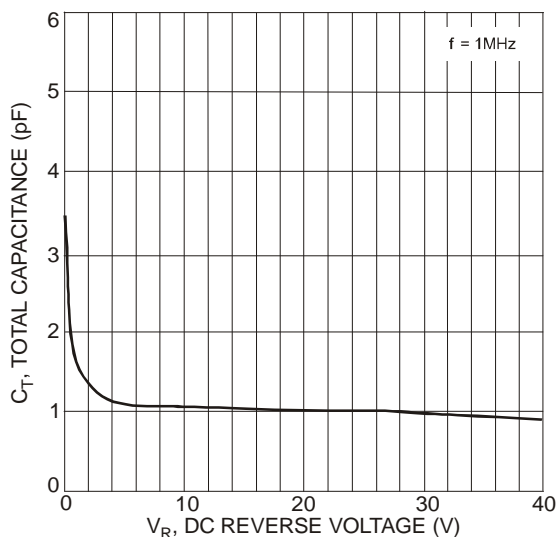


Fig. 5 Total Capacitance vs. Reverse Voltage Per Element

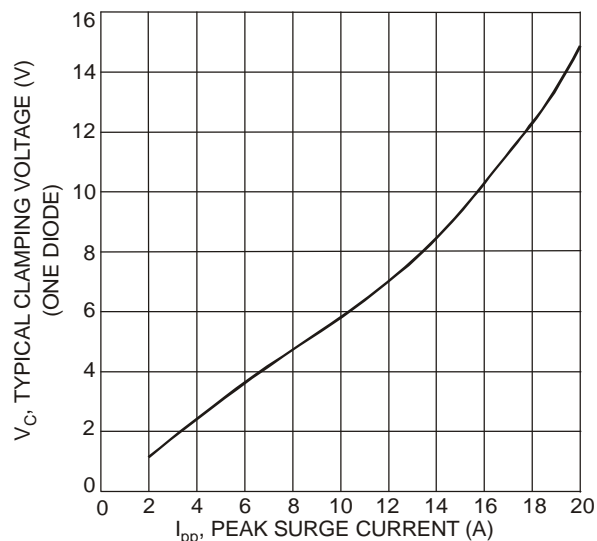
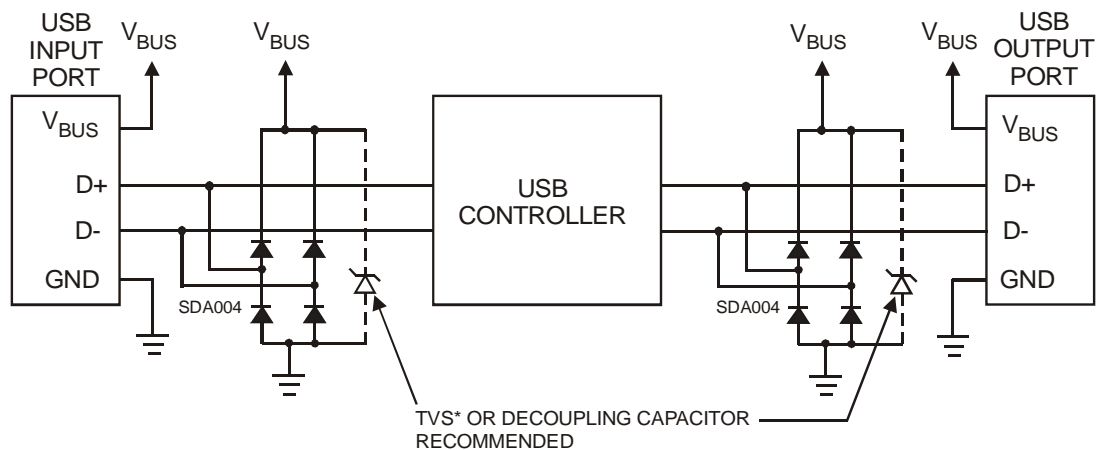


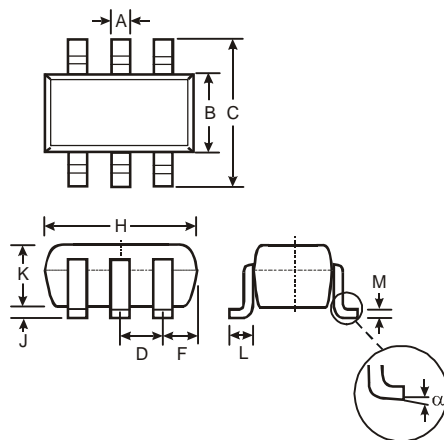
Fig. 6 6100-4-5 8x20µs Surge Response, Per Element



* MMBZ6V8AL OR EQUIVALENT

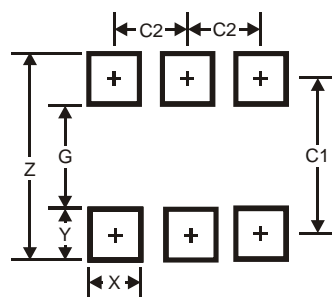
ESD PROTECTION - USB APPLICATION

Package Outline Dimensions



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

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